

ABSTRACT OF THE INVENTION

LAND GRID ARRAY PACKAGED DEVICE AND METHOD OF FORMING SAME

A method of packaging an integrated circuit die (12) includes the steps of forming an array of soft conductive balls (14) in a fixture (30) and flattening opposing sides of the balls. The flattened balls are then transferred from the fixture to a mold masking tape (36). A first side of the IC die is attached to the balls with a die attach adhesive (16) and then wire bonding pads (20) on the die are electrically connected directly to respective balls with wires (22). An encapsulant (24) is formed over the die, the electrical connections, and a top portion of the formed balls. The tape is removed and adjacent, encapsulated dice are separated via saw singulation. The result is an encapsulated IC having a bottom side with exposed balls.